

## April 16 (Wed.)

9:30	<p style="text-align: center;"><b>WA1: Advanced Packaging</b></p> <p><b>Chairperson: B. Olson (Motorola)</b> <b>H. Nishida (International Display Technology)</b></p> <ol style="list-style-type: none"> <li>1. Fluidic Self Assembly as Applied to Electronics Packaging G. Gengel, <i>Alien Technology / U.S.A.</i></li> <li>2. Improvements in the Reliability of 48 f<math>\bar{E}</math>m Laser Microvias for the Surface Laminar Circuit T. Yamada, <i>IBM Japan / Japan</i></li> <li>3. Development of Fine Pitch Lead Frames and Die tools M. Kitajima, <i>Shinko Electric Industries / Japan</i></li> <li>4. A Placement Technique for Wafer Scale Integrated Circuit A. Kanasugi, <i>Tokyo Denki University / Japan</i></li> </ol>	<p style="text-align: center;"><b>WB1: Design and Testing</b></p> <p><b>Chairperson: P. Guilbault (Bull SA)</b> <b>S. Kitajo (NEC)</b></p> <ol style="list-style-type: none"> <li>1. Improvement of Reliability Test for Laser LIT Repair on XGA LCD Module T. Wada, <i>International Display Technology / Japan</i></li> <li>2. A Study on Newly Developed Flatbed Type By-pass Capacitor for Effective Reducing Semiconductor Radiation Noise C. Igarashi, <i>Tohoku Ricoh / Japan</i></li> <li>3. Ultra Fine Pitch Probing Technology to Realize High Performance Wafer Testing M. Tanioka, Y. Shirai, K. Kojima, K. Takahashi, <i>Association of Super-Advanced Electronics Technologies / Japan</i></li> <li>4. New Probe Tip Fabricated by LIGA Process for Cleaning-free Test T. Haga, <i>Sumitomo Electric Industries / Japan</i></li> </ol>
11:10	<b>BREAK</b>	
11:20	<ol style="list-style-type: none"> <li>5. Low Temperature Si Direct Bonding Using Plasma-assisted Method T.H. Kim, M.M.R. Howlader, T. Suga, <i>University of Tokyo / Japan</i></li> <li>6. Study on Assembly Technologies in Chip on Film (COF) Package D.H.Y. Kuo, J. Liu, D. Chen, G.S. Shen, M.L. Huang, <i>Chipmos Technologies, C.L. Chung, S.L. Fu, I-Shou University / Taiwan</i></li> <li>7. Low Temperature Bonding of Silicon/Quartz and Quartz/Quartz Wafers by Surface Activated Bonding Process M.M.R. Howlader, T.H. Kim, T. Suga, <i>University of Tokyo / Japan</i></li> <li>8. High Density Wiring Technology and Evaluation with Cu/Photosensitive-BCB Multi-layer Structure K. Nakayama, <i>Dai Nippon Printing / Japan</i></li> </ol>	<ol style="list-style-type: none"> <li>5. Electric Field Application Method Effective for Pin Open Detection Based on Supply Current in CMOS Logic Circuits M. Hashizume, M. Ichimiya, H. Yotsuyanagi, T. Tamesada, <i>The University of Tokushima / Japan</i></li> <li>6. Visualization of Solder Joint Shape by Super-immersion Ultrasound H. Tohmyoh, M. Saka, <i>Tohoku University / Japan</i></li> <li>7. Method for Monitoring Solder Paste Printing Process T. Liukkonen, <i>Nokia, A. Tuominen, Tampere University of Technology / Finland</i></li> <li>8. Thermal Performance of Flip Chip Packages: Numerical Study of Thermo-mechanical Interactions M.-L. Sham, J.-K. Kim, <i>Hong Kong University of Science &amp; Technology / Hong Kong, J.-H. Park, Sejong University / Korea</i></li> </ol>
13:00	<b>LUNCH TIME</b>	
15:00	<b>WELCOME SPEECH</b>	
15:05	<b>AWARDING CEREMONY</b>	
15:15	<b>Invited Speech</b>	
15:20	<p><b>Chairperson: S. Wakabayashi (Shinko Electric Industries)</b></p> <p style="text-align: center;"><b>IMAPS - Status and Future Directions</b></p> <p style="text-align: center;">Dr. Peter Barnwell <i>President, IMAPS North America / U.S.A.</i></p> <p style="text-align: center;"><b>Advanced Flip Chip Technology and its Application in Europe</b></p> <p style="text-align: center;">Dr. Elke Zakel <i>Pac Tech - Packaging Technologies GmbH / Germany</i></p>	
17:00		
18:00	<b>WELCOME RECEPTION</b>	
	<p>The Harbor Circus Dai-ichi Hotel Tokyo Seafort, 3F.</p>	
20:00		



8:30	<p align="center"><b>FA1: 3D Packaging</b></p> <p><b>Chairperson: C.E. Bauer (Tech Lead)</b> <b>T. Satoh (Sharp)</b></p> <ol style="list-style-type: none"> <li>Wafer Level Packaging for RF MEMS Device T. Masai, <i>Omron / Japan</i></li> <li>High-density Through-hole Interconnections in a Silicon Substrate H. Nakamura, H. Wada, K. Itoi, S. Yamamoto, T. Suematsu, T. Takizawa, <i>Fujikura / Japan</i></li> <li>Development of Die Level Stacked Packaging I. Miyazawa, K. Matsui, K. Hara, Y. Matsuo, M. Ishii, Y. Yokoyama, <i>Seiko Epson / Japan</i></li> <li>Superfine Pitch Ultrasonic Bonding Technology on 3D Stacked LSI Y. Akiyama, R. Kajiwara, N. Tanaka, K. Tanida, M. Umemoto, Y. Tomita, M. Tago, K. Takahashi, <i>Association of Super-Advanced Electronics Technologies / Japan</i></li> <li>New Folded and Stacked 3D Multiple Die Packaging V. Solberg, <i>Tessera Technologies / U.S.A.</i></li> </ol>	<p align="center"><b>FB1: Pb-free Solder</b></p> <p><b>Chairperson: C.W.C. Lin (Bridge Semiconductor)</b> <b>H. Sawai (Tohtec)</b></p> <ol style="list-style-type: none"> <li>Development of the Sn-Zn-Al Solder Alloys M. Kitajima, <i>Fujitsu / Japan</i></li> <li>Solderability and Interface Property of Sn-Zn-Bi on Metal Substrates Y.-S. Kim, C.-W. Whang, K. Suganuma, <i>Osaka University / Japan</i></li> <li>Lead Free Solders with High Mechanical Reliability M. Amagai, <i>Texas Instruments, Japan</i>, Y. Toyoda, <i>Senju Metal Industry / Japan</i></li> <li>Comparison of Creep Behaviour of Sn-Ag-Cu Lead-free Solder System with Bismuth and Indium Addition C.M.L. Wu, C.M.T. Law, K.P. Tse, J.K.L. Lai, <i>City University of Hong Kong, / Hong Kong</i>, J. Liu, <i>Chalmers University of Technology / Sweden</i></li> <li>Interfacial Reaction of Sn-based Lead-free Solder with Fe-42Ni Substrate C.-W. Hwang, K. Suganuma, <i>Osaka University / Japan</i></li> </ol>
<b>BREAK</b>		
10:50	<p align="center"><b>FA2: Materials II</b></p> <p><b>Chairperson: C.M.L. Wu (City University of Hong Kong)</b> <b>M. Otsuka (Shibaura Institute of Technology)</b></p> <ol style="list-style-type: none"> <li>Characteristics of Conductive Adhesive for High Conductivity in Electronics Packaging W. Jeong, <i>Osaka University / Japan</i></li> <li>Excellent Reliability of Plastic Cored Solder Ball N. Okinaga, <i>Sekisui Chemical / Japan</i></li> <li>Low Temperature Curable Anisotropic Conductive Film for Input Lead Bonding of Liquid Crystal Display (LCD) Modules T. Fujinawa, <i>Hitachi Chemical / Japan</i></li> <li>Joining Silicon Carbide/Aluminum Composite M. Nakata, <i>Osaka University / Japan</i></li> </ol>	<p align="center"><b>FB2: LTCC</b></p> <p><b>Chairperson: G. Janusz (Private Institute of Electronic Engineering)</b> <b>S. Uegaki (Kyocera)</b></p> <ol style="list-style-type: none"> <li><b>Self Constrained LTCC Technology Addresses Challenges in Microelectronics Packaging (Session Invite)</b> P. Barnwell, F. Lautzenhiser, <i>Heraeus Circuit Materials Division / U.S.A.</i></li> <li>A Study on the RuO<sub>2</sub> System Pb-free Thick Film Resistors K. Akabane, <i>Musashi Institute of Technology, C. Higuchi, Tanaka Kikinokyo Kogyo, I. Kaneko, Musashi Institute of Technology / Japan</i></li> <li>Comparison of LTCC Passive Components in Different Structure T. Hanawa, I. Urvas, <i>Nokia-Japan / Japan</i></li> <li>Package Technologies for High Speed Digital Devices Y. Furukubo, <i>Kyocera / Japan</i></li> </ol>
<b>LUNCH TIME</b>		
13:30	<p align="center"><b>FA3: Flip-chip I</b></p> <p><b>Chairperson: J. Maattanen (Elcoteq Network)</b> <b>A. Okuno (Sanyu Rec)</b></p> <ol style="list-style-type: none"> <li><b>Sub-100 Micron Pitch Flip Chip Bumping &amp; Assembly (Session Invite)</b> C.E. Bauer, <i>TechLead / U.S.A.</i>, F.J. Wu, <i>Chipbond Technology / Taiwan</i></li> <li>Bumpless Flip Chip CSP and BGA for Memory Devices C.W.C. Lin, S.C.L. Chiang, T.K.A. Yang, <i>Bridge Semiconductor / Taiwan</i></li> <li>Flip Chip Bonding Technology Using Evaporating Type Flux A. Tanahashi, M. Yoshino, N. Imaizumi, Y. Otani, T. Nagasaka, <i>Denso / Japan</i></li> <li>Flux-less Solder Flip Chip Bonding Technique Using Non-conductive Paste A. Watanabe, <i>Toray Engineering / Japan</i></li> <li>The Latest Liquid Underfill Materials for Flip-chip Applications H. Yoshii, <i>Namics / Japan</i></li> </ol>	<p align="center"><b>FB3: Optoelectronics II</b></p> <p><b>Chairperson: B. Choi (Information &amp; Communications University)</b> <b>Y. Ando (Fujikura)</b></p> <ol style="list-style-type: none"> <li>A High Performance Small Form Factor Pluggable Transceiver for up to 80km Reach at 2.5Gbps S. Priyadarshi, I. Khalouf, K. Kamath, J. Booker, S.P. Scrac, J. Sheridan, R. Bylsma, J.P. Keska, <i>Agere Systems / U.S.A.</i></li> <li>Fabrication of TEC Using by Photosensitive Fibers and Analysis of Alignment between LD and TEC S.-J. Jee, M.-S. Lee, <i>Information and communications university, C.-S. Park, H.-I. Lee, Phoco / Korea</i></li> <li>Optical Interconnections with Polymer Waveguide Built up on Printed Wiring Boards T. Nonaka, <i>Toray Industries, T. Suzuki, Matsushita Electric Industrial, S.-Y. Cho, N. M. Jakerst, Georgia Institute of Technology / U.S.A.</i></li> <li>Low Cost Intra-board Level Optical Interconnection Using Fluorinated Polyimide Waveguide Film T. Shioda, N. Takamatsu, K. Suzuki, <i>Mitsui Chemicals / Japan</i></li> <li>Optical Wave Guide for Interconnect Fabricated by Molding Process F. Yamada, <i>IBM Japan / Japan</i></li> </ol>
<b>COFFEE BREAK</b>		
15:50	<p align="center"><b>FA4: Flip-chip II</b></p> <p><b>Chairperson: E. Zakei (PacTech)</b> <b>A. Makabe (Seiko Epson)</b></p> <ol style="list-style-type: none"> <li>High Density Flip Chip Assembly on Novel Printed Circuit Board T. Uusluoto, <i>Tampere University of Technology, J. Maattanen, P. Palm, Elcoteq Network, A. Tuominen, Tampere University of Technology / Finland</i></li> <li>Pb-free Solder Bump Bonding for High Pin Count Flip-chip BGA Using Organic Substrate E. Hayashi, <i>Mitsubishi Electric / Japan</i></li> <li>Plastic Flip-chip Fine Package Fabricated on Organic Substrate N. Masumoto, K. Tanaka, K. Mitsuka, M. Takahashi, <i>New Japan Radio / Japan</i></li> <li>Some Advanced Approaches to Improve the Cost Performance of the FC-BGA Substrates K. Kawasaki, S. Kodama, Y. Yamaji, T. Nishio, <i>IBM Japan / Japan</i></li> <li>The Use of Infrared Imaging to Define Reliability in Assembly of ACA Flip-chips Using Thin Substrates P. Jalonen, <i>Satakunta Polytechnic, J. Maattanen, Elcoteq Network, A. Ekholm, P. Reunamo, Satakunta polytechnic / Finland</i></li> </ol>	<p align="center"><b>FB4: High Speed/High Frequency Package</b></p> <p><b>Chairperson: S. Priyadarshi (Agere Systems)</b> <b>F. Uchikoba (TDK)</b></p> <ol style="list-style-type: none"> <li>Study on Interconnection Technology for over 1Gbps On-board Signal Transmission K. Yamagishi, <i>Mitsubishi Electric / Japan</i></li> <li>Development of Small Size Millimeter Wave Transceiver for Fixed Wireless Access M. Ishida, K. Gomi, N. Matsui, <i>Toshiba / Japan</i></li> <li>The New Thick-film Hybrid Microwave Elements for a Novel Light Efficacy Microwave Powered Light Sources J. Gondek, <i>Private Institute of Electronic Engineering, S. Kordowiak, Cracow University of Technology, P. Szatynski, TELPOD, J. Kocol, Technical School of Telecommunication / Poland</i></li> <li>Effect of Ground Vias on Performance of Interconnections Embedded in Multilayer PCB's T. Kushta, K. Narita, H. Tohya, <i>NEC / Japan</i></li> <li>Replacement of Bypass Capacitor to Transmission Line for over GHz Power Supply System K. Saito, <i>University of Tokyo, Y. Akiyama, Meisei University, T. Usami, University of Tokyo, K. Otsuka, Meisei University, T. Suga, University of Tokyo / Japan</i></li> </ol>
17:55		